



# LIST OF REFERENCES CITED BY APPLICANT

(Use additional sheets if necessary)

ATTY. DOCKET NO.  
100970.665047US1

SERIAL NO.  
10026135

APPLICANT  
Pedigo, Jesse et al

FILING DATE  
20 December 2001

GROUP  
To be determined

## U.S. PATENT DOCUMENTS

EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
	AA	6,454,154	08/24/02	Filling Device	228	33	12/28/00
	BB	5,893,404	04/13/99	Method and Apparatus for Metal Solid Freeform Fabrication Utilizing Partially Solidified Metal Slurry	164	71.1	09/20/96
	CC	4,498,275	02/12/85	Rotary Filling and Capping Apparatus	53	506	07/06/81
	DD						
	EE						
	FF						
	GG						
	HH						
	II						

## FOREIGN PATENT DOCUMENTS

		DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
							YES	NO
	JJ							
	KK							
	LL							
	MM							
	NN							

## OTHER REFERENCES (Including Author, Title, Date, Pertinent Pages, Etc.)

	OO	
EXAMINER	DATE CONSIDERED	

\*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

## LIST OF REFERENCES CITED BY APPLICANT

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APP. NO. 100065-00471/US2

APPLICANT

Jesse Pedigo, et al

FILING DATE

12/20/01

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## U.S. PATENT DOCUMENTS

TC 1700

FIG. NO. IN DRAWING	PATENT NO.	DATE	TITLE	CLASS	NO. OF PAGES	DATE OF PUBLICATION
15	3,601,523	08/24/71	Through Hole Connectors	174	68.5	06/19/70
	4,106,187	08/15/78	Curved Rigid Printed Circuit Boards	29	625	01/16/76
	4,283,243	08/11/81	Use of Photosensitive Stratum to Create Through-Hole Connections in Circuit Boards	156	237	03/20/80
	4,360,570	11/23/82	Use of Photosensitive Stratum to Create Through-Hole Connections in Circuit Boards	428	596	06/15/81
	4,622,239	11/11/86	Method and Apparatus for Dispensing Viscous Materials	427	96	02/18/86
	4,700,474	10/20/87	Apparatus and Method for Temporarily Sealing Holes in Printed Circuit Boards	29	846	11/26/86
	4,777,721	10/18/88	Apparatus and Method for Temporarily Sealing Holes in Printed Circuit Boards Utilizing a Thermodeformable Material	29	846	10/15/87
	4,783,247	11/8/88	Method and Manufacture for Electrically Insulating Base Material Used in Plated-Through Printed Circuit Panels	204	181.1	05/15/86
	4,884,337	12/05/89	Method for Temporarily Sealing Holes in Printed Circuit Boards Utilizing a Thermodeformable Material	29	846	10/15/87
	4,954,313	09/04/90	Method and Apparatus for Filling High Density Vias	419	9	02/03/89
	4,964,948	10/23/90	Printed Circuit Board Through Hole Technique	156	659	11/13/89
	4,995,941	02/26/91	Method of Manufacture Interconnect Device	156	630	05/15/89
	5,053,921	10/01/91	Multilayer Interconnect Device and Method of Manufacture Thereof	361	386	10/23/90
	5,058,265	10/22/91	Method for Packaging a Board of Electronic Components	29	852	09/10/90
	5,117,069	05/26/92	Circuit Board Fabrication	174	261	09/28/90
	5,133,120	07/28/92	Method of Filling Conductive Material into Through Holes of Printed Wiring Board	29	852	03/15/91
	5,145,691	09/08/92	Apparatus for Packing Filler into Through-Holes or the Like in a Printed Circuit Board	425	110	03/22/91
	5,220,723	06/22/93	Process for Preparing Multi-Layer Printed Wiring Board	29	830	11/04/91
15	5,274,916	01/04/94	Method of Manufacturing Ceramic Multilayer Electronic Component	29	848	12/17/92